

1

2

3

4

5

6

1

2

3

4

5

6

Layer

Name

Material

Thickness

Constant

Board Layer Stack

Top Overlay

Top Solder

Solder Resist

0.40mil

3.5

1

Top Layer

2.80mil

Dielectric 1

FR-4 High Tg

10.00mil

4.2

2

Signal Layer 1

1.42mil

Dielectric2

FR-4 High Tg

32.00mil

4.2

3

Signal Layer 2

1.42mil

Dielectric 3

FR-4 High Tg

10.00mil

4.2

4

Bottom Layer

2.80mil

Bottom Solder

Solder Resist

0.40mil

3.5

Bottom Overlay

Total board thickness: 61.23mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

1

2

3

4

5

6

1

2

3

4

5

6

Symbol

Quantity

Finished Hole Size

Plated

Hole Type

Drill Layer Pair

Hole Tolerance

☆

3

7.87mil (0.200mm)

PTH

Round

Top Layer - Bottom Layer

▽

65

8.00mil (0.203mm)

PTH

Round

Top Layer - Bottom Layer

⊗

56

10.00mil (0.254mm)

PTH

Round

Top Layer - Bottom Layer

⊗

7

40.00mil (1.016mm)

PTH

Round

Top Layer - Bottom Layer

○

4

98.43mil (2.500mm)

PTH

Round

Top Layer - Bottom Layer

□

4

125.98mil (3.200mm)

PTH

Round

Top Layer - Bottom Layer

139 Total

2000.00

2000.00

1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: SR066

REV: A

SUN REV: Not in version control

TEXAS INSTRUMENTS

LAYER NAME = Microsection

TID #: N/A

GENERATED : 10/23/2024 11:34:43 AM

TEXAS INSTRUMENTS

PLOT NAME = Fabrication Drawing

SCALE: 1.00

ALTUM DESIGNER VERSION: 24.4.1.13

1

2

3

4

5

6

1

2

3

4

5

6

Layer

Name

Material

Thickness

Constant

Board Layer Stack

Top Overlay

Top Solder

Solder Resist

0.40mil

3.5

1

Top Layer

2.80mil

Dielectric 1

FR-4 High Tg

10.00mil

4.2

2

Signal Layer 1

1.42mil

Dielectric2

FR-4 High Tg

32.00mil

4.2

3

Signal Layer 2

1.42mil

Dielectric 3

FR-4 High Tg

10.00mil

4.2

4

Bottom Layer

2.80mil

Bottom Solder

Solder Resist

0.40mil

3.5

Bottom Overlay

Total board thickness: 61.23mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

1

2

3

4

5

6

1

2

3

4

5

6

Symbol

Quantity

Finished Hole Size

Plated

Hole Type

Drill Layer Pair

Hole Tolerance

☆

3

7.87mil (0.200mm)

PTH

Round

Top Layer - Bottom Layer

▽

65

8.00mil (0.203mm)

PTH

Round

Top Layer - Bottom Layer

⊗

56

10.00mil (0.254mm)

PTH

Round

Top Layer - Bottom Layer

⊗

7

40.00mil (1.016mm)

PTH

Round

Top Layer - Bottom Layer

○

4

98.43mil (2.500mm)

PTH

Round

Top Layer - Bottom Layer

□

4

125.98mil (3.200mm)

PTH

Round

Top Layer - Bottom Layer

139 Total

2000.00

2000.00

1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: SR066

REV: A

SUN REV: Not in version control

TEXAS INSTRUMENTS

LAYER NAME = Microsection

TID #: N/A

GENERATED : 10/23/2024 11:34:43 AM

TEXAS INSTRUMENTS

PLOT NAME = Fabrication Drawing

SCALE: 1.00

ALTUM DESIGNER VERSION: 24.4.1.13

1

2

3

4

5

6

1

2

3

4

5

6

Layer

Name

Material

Thickness

Constant

Board Layer Stack

Top Overlay

Top Solder

Solder Resist

0.40mil

3.5

1

Top Layer

2.80mil

Dielectric 1

FR-4 High Tg

10.00mil

4.2

2

Signal Layer 1

1.42mil

Dielectric2

FR-4 High Tg

32.00mil

4.2

3

Signal Layer 2

1.42mil

Dielectric 3

FR-4 High Tg

10.00mil

4.2

4

Bottom Layer

2.80mil

Bottom Solder

Solder Resist

0.40mil

3.5

Bottom Overlay

Total board thickness: 61.23mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

1

2

3

4

5

6

1

2

3

4

5

6

Symbol

Quantity

Finished Hole Size

Plated

Hole Type

Drill Layer Pair

Hole Tolerance

☆

3

7.87mil (0.200mm)

PTH

Round

Top Layer - Bottom Layer

▽

65

8.00mil (0.203mm)

PTH

Round

Top Layer - Bottom Layer

⊗

56

10.00mil (0.254mm)

PTH

Round

Top Layer - Bottom Layer

⊗

7

40.00mil (1.016mm)

PTH

Round

Top Layer - Bottom Layer

○

4

98.43mil (2.500mm)

PTH

Round

Top Layer - Bottom Layer

□

4

125.98mil (3.200mm)

PTH

Round

Top Layer - Bottom Layer

139 Total

2000.00

2000.00

1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: SR066

REV: A

SUN REV: Not in version control

TEXAS INSTRUMENTS

LAYER NAME = Microsection

TID #: N/A

GENERATED : 10/23/2024 11:34:43 AM

TEXAS INSTRUMENTS

PLOT NAME = Fabrication Drawing

SCALE: 1.00

ALTUM DESIGNER VERSION: 24.4.1.13

1

2

3

4

5

6

1

2

3

4

5

6

Layer

Name

Material

Thickness

Constant

Board Layer Stack

Top Overlay

Top Solder

Solder Resist

0.40mil

3.5

1

Top Layer

2.80mil

Dielectric 1

FR-4 High Tg

10.00mil

4.2

2

Signal Layer 1

1.42mil

Dielectric2

FR-4 High Tg

32.00mil

4.2

3

Signal Layer 2

1.42mil

Dielectric 3

FR-4 High Tg

10.00mil

4.2

4

Bottom Layer

2.80mil

Bottom Solder

Solder Resist

0.40mil

3.5

Bottom Overlay

Total board thickness: 61.23mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

1

2

3

4

5

6

1

2

3

4

5

6

Symbol

Quantity

Finished Hole Size

Plated

Hole Type

Drill Layer Pair

Hole Tolerance

☆

3

7.87mil (0.200mm)

PTH

Round

Top Layer - Bottom Layer

▽

65

8.00mil (0.203mm)

PTH

Round

Top Layer - Bottom Layer

⊗

56

10.00mil (0.254mm)

PTH

Round

Top Layer - Bottom Layer

⊗

7

40.00mil (1.016mm)

PTH

Round

Top Layer - Bottom Layer

○

4

98.43mil (2.500mm)

PTH

Round

Top Layer - Bottom Layer

□

4

125.98mil (3.200mm)

PTH

Round

Top Layer - Bottom Layer

139 Total

2000.00

2000.00

1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: SR066

REV: A

SUN REV: Not in version control

TEXAS INSTRUMENTS

LAYER NAME = Microsection

TID #: N/A

GENERATED : 10/23/2024 11:34:43 AM

TEXAS INSTRUMENTS

PLOT NAME = Fabrication Drawing

SCALE: 1.00

ALTUM DESIGNER VERSION: 24.4.1.13

1

2

3

4

5

6

1

2

3

4

5

6

Layer

Name

Material

Thickness

Constant

Board Layer Stack

Top Overlay

Top Solder

Solder Resist

0.40mil

3.5

1

Top Layer

2.80mil

Dielectric 1

FR-4 High Tg

10.00mil

4.2

2

Signal Layer 1

1.42mil

Dielectric2

FR-4 High Tg

32.00mil

4.2

3

Signal Layer 2

1.42mil

Dielectric 3

FR-4 High Tg

10.00mil

4.2

4

Bottom Layer

2.80mil

Bottom Solder

Solder Resist

0.40mil

3.5

Bottom Overlay

Total board thickness: 61.23mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

FR-408

☒ FR-4 High Tg

☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENG) ☐ ENEPIG

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.

PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☐ XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

☐ XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE

☐ OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☐ LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

1

2

3

4

5

6

1

2

3

4

5

6

Symbol

Quantity

Finished Hole Size

Plated

Hole Type

Drill Layer Pair

Hole Tolerance

☆

3

7.87mil (0.200mm)

PTH

Round

Top Layer - Bottom Layer

▽

65

8.00mil (0.203mm)

PTH

Round

Top Layer - Bottom Layer

⊗

56

10.00mil (0.254mm)

PTH

Round

Top Layer - Bottom Layer

⊗

7

40.00mil (1.016mm)

PTH

Round

Top Layer - Bottom Layer

○

4

98.43mil (2.500mm)

PTH

Round

Top Layer - Bottom Layer

□

4

125.98mil (3.200mm)

PTH

Round

Top Layer - Bottom Layer

139 Total

2000.00

2000.00

1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: SR066

REV: A

SUN REV: Not in version control

TEXAS INSTRUMENTS

LAYER NAME = Microsection

TID #: N/A

GENERATED : 10/23/2024 11:34:43 AM

TEXAS INSTRUMENTS

PLOT NAME = Fabrication Drawing

SCALE: 1.00

ALTUM DESIGNER VERSION: 24.4.1.13

1

2

3

4

5

6

1

2

3

4

5

6

Layer

Name

Material

Thickness

Constant

Board Layer Stack

Top Overlay

Top Solder

Solder Resist

0.40mil

3.5

1

Top Layer

2.80mil

Dielectric 1

FR-4 High Tg

10.00mil

4.2

2

Signal Layer 1

1.42mil

Dielectric2

FR-4 High Tg

32.00mil

4.2

3

Signal Layer 2

1.42mil

Dielectric 3

FR-4 High Tg

10.00mil

4.2

4

Bottom Layer

2.80mil

Bottom Solder

Solder Resist

0.40mil

3.5

Bottom Overlay

Total board thickness: 61.23mil

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 0.2 mm

MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C